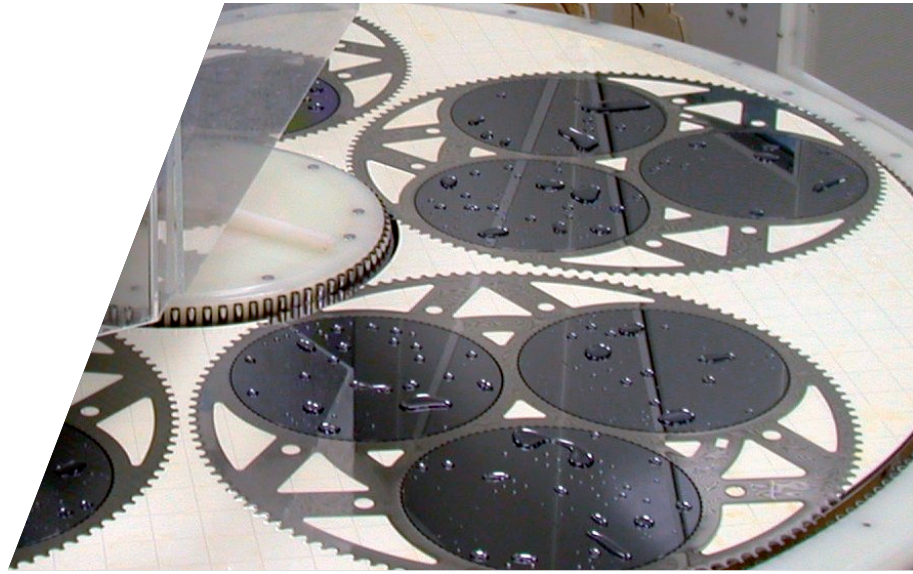
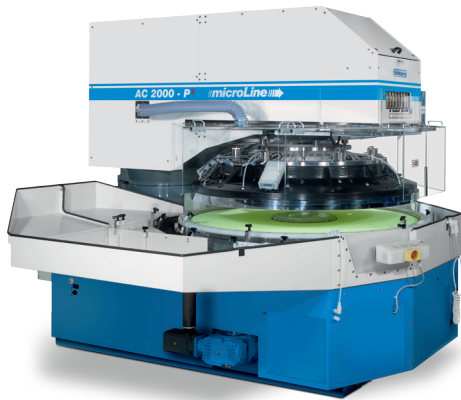


AC microLine® 2000-P³

PRIME WAFER DOUBLE-SIDE POLISHING SYSTEM



15 WAFER/BATCH 300 mm WAFER

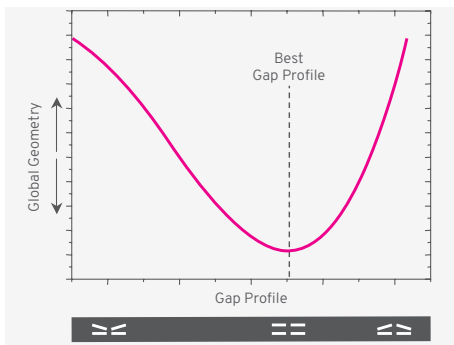
THE MOST COMPREHENSIVE SOLUTION

- ✓ Unique and patented UPAC (Upper Platen Adaptive Control) System
- ✓ 2 Gap Sensors
- ✓ Benchmark in precision, quality, efficiency, and cost of ownership
- ✓ The most flexible machine for supporting all future wafer requirements

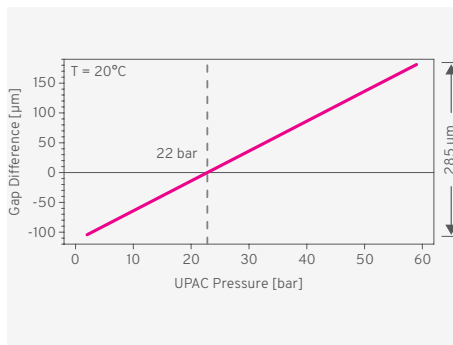
BENCHMARK IN PRECISION AND FLEXIBILITY

HIGHLIGHTS AC microLine® 2000-P³

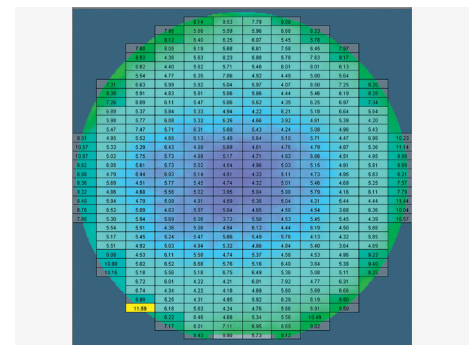
- ☑ Unique and patented UPAC (Upper Platen Adaptive Control) System
- ☑ Monitoring of the cooling lubricant flow rate
- ☑ Loop control
- ☑ First-Class customer support for the highest machine availability and productivity
- ☑ Integrated high precision interferometric device for in-situ measurement of the wafer thickness
- ☑ High-Pressure Conditioner
- ☑ Slurry Recycling Station
- ☑ Slurry Pressure Distribution
- ☑ Integrated Process Data Recording (DataCare®)
- ☑ Industry 4.0
- ☑ Touch Screen



The importance of the gap – Perfect wafer flatness requires gap adjustment



UPAC System – Global Measurement



SFQR Map – 300mm Si-Wafer
SFQR Values: Max: 11.59 nm, Average: 5.98 nm

TECHNICAL DATA	AC microLine® 2000-P ³
Wheel diameter [mm]	1935
Ring width [mm]	686
Max. load pressure [daN]	4000
Upper / lower drive power [kW]	46
Upper / lower drive speed [rpm]	0–40
Center drive power [kW]	7.5
Center drive speed [rpm]	0–50
Outer drive power [kW]	9.5
Outer drive speed [rpm]	0–7.5
Working wheel cooling	Labyrinth
Dimensions [H × W × D] [mm]	3000 × 4200 × 3900
Weight [kg]	21000
Load capacity	
300 mm [12"] Wafer	15 pieces
200 mm [8"] Wafer	30 pieces

GET IN TOUCH WITH US TODAY
TOGETHER WE WILL FIND A SOLUTION
FOR YOUR REQUIREMENTS

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